



Material Content Data Sheet



Sales Product Name	IFX1054G			Issued		27. September 2017		
MA#	MA000981502							
Package	PG-DSO-14-1			Weight*		144.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.050	4.89	4.89	48934	48934
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		419	
	non noble metal	iron	7439-89-6	1.207	0.84		8377	
	non noble metal	copper	7440-50-8	49.007	34.02	34.91	340157	349058
wire	noble metal	gold	7440-57-5	0.247	0.17	0.17	1713	1713
encapsulation	organic material	carbon black	1333-86-4	0.164	0.11		1136	
	plastics	epoxy resin	-	7.530	5.23		52267	
	inorganic material	silicondioxide	60676-86-0	74.156	51.48	56.82	514720	568123
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8511	8511
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7148	7148
glue	plastics	acrylic resin	-	0.523	0.36		3633	
	noble metal	silver	7440-22-4	1.856	1.29	1.65	12880	16513
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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